

SEMICONDUCTOR MEMORY INTEGRATED CIRCUIT

ABSTRACT OF THE DISCLOSURE

In a semiconductor memory integrated circuit (IC), a plurality of first data IO pads, a plurality of address and instruction pads, and a plurality of second data IO/address pads, are arranged in groups adjacent each other. Each of the plurality of the second data IO/address pads is used as a second data IO pad in response to a control signal when packaged into a first package form and is used as an address pad in response to the control signal when packaged into a second package form. The semiconductor memory IC of the present invention can selectively use a portion of pads as data IO pads or address/instruction pads, and thus the IC is compatible for use with different types of packages. The semiconductor memory IC of the present invention further allows for simplified wire bonding when it is packaged into different types of packages, and thus the possibility of failure of the semiconductor memory device is reduced.

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